

View Online at https://aerobasegroup.com/nsn/5910-01-400-5905

| Body Style: |
|--|
| Chip type |
| Reliability Indicator: |
| Established |
| Reliability Failure Rate Level In Percent: |
| 0.001 |
| Terminal Length: |
| 0.015 inches |
| Body Length: |
| Between 0.090 inches and 0.145 inches |
| Body Width: |
| Between 0.090 inches and 0.130 inches |
| Body Height: |
| Between 0.030 inches and 0.102 inches |
| Schematic Diagram Designator: |
| No common or grounded electrode (s) |
| Insulation Resistance At Maximum Operating Temp: |
| 10000.0 megohms |
| Capacitance Value Per Section: |
| 680.000 picofarads single section |
| Nonderated Operating Temp: |
| Between -55.0 degrees celsius and 125.0 degrees celsius |
| Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: |
| 90.0 single section |
| Nonderated Continuous Voltage Rating And Type Per Section: |
| 50.0 dc single section |
| Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius: |
| -20.0/+20.0 single section |
| Tolerance Range Per Section: |
| -5.00/+5.00 percent single section |
| Case Material: |
| Ceramic or glass |
| Insulation Resistance At Reference Temp: |
| 1000000.0 megohms |
| Dissipation Factor At Reference Tempurature In Percent: |
| 0.050 |
| Terminal Surface Treatment: |
| Solder |
| Test Data Document: |
| 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification |
| format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain |
| environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.). |
| |

Terminal Type And Quantity:

2 bonding pad



Specification Data:

81349-mil-c-55681/04 government specification

Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

A010b0